

PolarHT[™] Power MOSFET

IXTC 62N15P IXTR 62N15P

V _{DSS}	=	150	V
D25	=	36	Α
R _{DS(on)}	≤	45	mΩ

(Electrically Isolated Tab)

N-Channel Enhancement Mode Avalanche Rated

Symbol	Test Conditions		Maximum Ratings			
V _{dss} V _{dgr}	$T_{J} = 25^{\circ} C \text{ to } 150^{\circ} T_{J} = 25^{\circ} C \text{ to } 150^{\circ} C$	°C °C; R _{GS} = 1 ΜΩ	150 150	V V		
V _{gs} V _{gsm}	Continuous Transient		± 20 ± 30	V V		
 _{D25} _{DM}	$T_c = 25^{\circ} C$ $T_c = 25^{\circ} C$, pulse	width limited by $T_{_{JM}}$	36 150	A A		
I _{AR} E _{AR} E _{AS}	$T_{c} = 25^{\circ} C$ $T_{c} = 25^{\circ} C$ $T_{c} = 25^{\circ} C$		50 30 1.0	A mJ J		
dv/dt	$I_{s} \leq I_{DM}$, di/dt ≤ 10 $T_{J} \leq 150^{\circ}$ C, R _G =	00 A/μs, V _{DD} ≤V _{DSS} , 10 Ω	10	V/ns		
P _D	T _c = 25° C		150	W		
T _J T _{JM} T _{stg}			-55 +175 150 -55 +150	3° 3° 3°		
TL	1.6 mm (0.062 in.) from case for 10 s	300	°C		
F _c	Mounting force	ISOPLUS220 ISOPLUS247	1165 / 2.515 20120 / 4.525	N/lb N/lb		
Weight		ISOPLUS220 ISOPLUS247	3	g		

SymbolTest ConditionsCh $(T_j = 25^{\circ} \text{ C} \text{ unless otherwise specified})Min.$				naracteristic Values Typ. Max.			
BV _{DSS}	$V_{_{\rm GS}}$ = 0 V, I $_{_{\rm D}}$ = 250 µA		150			V	
V _{GS(th)}	$V_{_{\rm DS}} = V_{_{\rm GS}}, I_{_{\rm D}} = 250 \ \mu A$		3.0		5.0	V	
I _{gss}	$V_{_{\rm GS}} = \pm 20 V_{_{\rm DC}}, V_{_{\rm DS}} = 0$				± 100	nA	
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	T _J = 125° C			10 200	μΑ μΑ	
R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 31 \text{ A}, \text{ Note}$	e 1			45	mΩ	



- ¹ UL recognized packages
- ¹ Silicon chip on Direct-Copper-Bond substrate
 - High power dissipation
 - Isolated mounting surface
- 2500V electrical isolation
- ¹ Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- Fast intrinsic diode

Advantages

- ¹ Easy to mount
- ¹ Space savings
- ¹ High power density

DS99622E(05/06)

IXYS

IXTC 62N15P IXTR 62N15P

Symbo	Test Conditions $(T_{J} = 25^{\circ}C)$	Cha unless	aracteris s otherwi	tic Va se sp	alues ecified)
		Min.	Тур.	Ma	х.
\mathbf{g}_{fs}	$V_{\rm DS}$ = 20 V; I _D = 31 A, Note 1	14	24		S
C _{iss})		2250		pF
$\mathbf{C}_{_{\mathrm{oss}}}$	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		660		pF
C _{rss})		185		pF
t _{d(on)})		27		ns
t,	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, \text{ I}_{D} = 62 \text{ A}$		38		ns
t _{d(off)}	$R_{g} = 10 \Omega (External)$		76		ns
t _r)		35		ns
$\mathbf{Q}_{g(on)}$)		70		nC
\mathbf{Q}_{gs}	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS} , I_{D} = 31 A		20		nC
\mathbf{Q}_{gd}	J		38		nC
R _{thJC}				1.0	°C/W
$\mathbf{R}_{\mathrm{thCS}}$			0.15		° C/W

Source-Drain Diode		Characteristic Values T = 25°C unless otherwise specifier			
Symbol Test Conditions		Min.	Тур.	Max.	
l _s	$V_{GS} = 0 V$			62	Α
I _{sm}	Repetitive			150	Α
V _{SD}	$I_F = I_S, V_{GS} = 0 \text{ V}, \text{ Note } 1$			1.5	V
t _{rr}	$I_{_{\rm F}}$ = 25 A, -di/dt = 100 A/µs		150		ns
Q _{RM} ∫	$V_{R} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		2.0		μC

Note 1: Pulse test, t \leq 300 µs, duty cycle d \leq 2 %;

2: Test current I I_{τ} = 62 A.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a preproduction design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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XYS MOSFETs and IGBTs are covered by 4,835,5 one or moreof the following U.S. patents: 4,850,0 4,881,1	924,931,844725,017,508065,034,796	5,049,961 5,063,307 5,187,117	5,237,481 5,381,025 5,486,715	6,162,665 6,259,123 B1 6,306,728 B1	6,404,065 B1 6,534,343 6,583,505	6,683,344 6,710,405B2 6,710,463	6,727,585 6,759,692 6771478 B2	7,005,734B2	

		ottom he ectrically 2, or 3.	atsink (P isolated	in 4) is from Pin
	INCH	IF S	MILLIN	IETERS
SYM	MIN	MAX	MIN	MAX
Δ	.157	.197	4.00	5.01
A2	.098	.118	2.50	3.00
<u> </u>	.035	.051	0.90	1.30
h2	.049	.065	1.25	1.65
b4	.093	.100	2.35	2.55
С	,028	,039	0.70	1.00
D	.591	.630	15.00	16.00
D1	.472	.512	12.00	13.00
E	.394	.433	10.00	11.00
E1	.295	.335	7.50	8.50
e	.100	BASIC	2.55	BASIC
L	.512	.571	13.00	14.50
L1	.118	.138	3.0D	3.50
T°			42.5°	47.5
			Ref: IXYS (CO 0177 R0

ISOPLUS220[™] (IXTC) Outline

ISOPLUS247 (IXTR) Outline





CVM	INCH	IES	MILLIMETERS		
2114	MIN	MAX	MIN	MAX	
Α	.190	.205	4.83	5.21	
A1	.090	.100	2.29	2.54	
A2	.075	.085	1.91	2.16	
Ь	.045	.055	1.14	1.40	
Ь1	.075	.084	1.91	2.13	
ь2	.115	.123	2.92	3.12	
С	.024	.031	0.61	0.80	
D	.819	.840	20.80	21.34	
E	.620	.635	15.75	16.13	
e	.215 BSC		5.45 BSC		
L	.780	.800	19.81	20.32	
L1	.150	.170	3.81	4.32	
Q	.220	.244	5.59	6.20	
R	.170	.190	4.32	4.83	
S	.520	.540	13.21	13.72	
Т	.620	.640	15.75	16.26	
U	.065	.080	1.65	2.03	



NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

Mouser Electronics

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IXYS: IXTR62N15P